

STGWT40H65DFB

Trench gate field-stop IGBT, HB series 650 V, 40 A high speed

Datasheet - production data

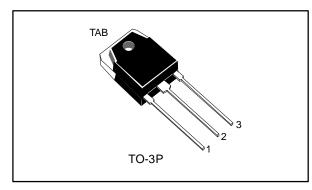
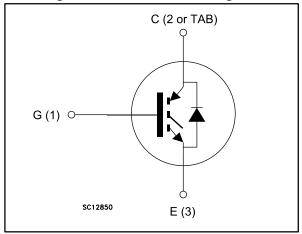


Figure 1: Internal schematic diagram



Features

- Maximum junction temperature: T_J = 175 °C
- High speed switching series
- Minimized tail current
- Tight parameter distribution
- Safe paralleling
- Low thermal resistance

Applications

- Photovoltaic inverters
- High frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the new HB series of IGBTs, which represents an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive VCE(sat) temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGWT40H65DFB	GWT40H65DFB	TO-3P	Tube

Contents STGWT40H65DFB

Contents

1	Electrical ratings		
2	Electric	cal characteristics	4
	2.1	Electrical characteristics (curves)	7
3	Test cir	·cuits	13
4	Packag	e information	14
	4.1	TO-3P package information	15
5	Revisio	n history	17

STGWT40H65DFB Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
Vces	Collector-emitter voltage (V _{GE} = 0)	650	٧
1-	Continuous collector current at T _C = 25 °C	80	А
lc	Continuous collector current at T _C = 100 °C	40	A
ICP ⁽¹⁾	Pulsed collector current	160	Α
V_{GE}	Gate-emitter voltage	±20	٧
	Continuous forward current at T _C = 25 °C	80	А
l _F	Continuous forward current at T _C = 100 °C	40	A
I _{FP} ⁽¹⁾	Pulsed forward current	160	Α
Ртот	Total dissipation at T _C = 25 °C	283	W
Tstg	Storage temperature range	- 55 to 150	္ခင
TJ	Operating junction temperature range	- 55 to 175	,

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
RthJC	Thermal resistance junction-case IGBT	0.53	
R _{th} JC	Thermal resistance junction-case diode	1.14	°C/W
RthJA	Thermal resistance junction-ambient	50	

 $^{^{(1)}}$ Pulse width limited by maximum junction temperature.

Electrical characteristics STGWT40H65DFB

2 Electrical characteristics

 $T_C = 25$ °C unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}, I_C = 2 \text{ mA}$	650			V
		$V_{GE} = 15 \text{ V}, I_{C} = 40 \text{ A}$		1.6	2	
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 40 A, T _J = 125 °C		1.7		V
	voltage	V _{GE} = 15 V, I _C = 40 A, T _J = 175 °C		1.8		
		I _F = 40 A		1.7	2.45	
V_{F}	Forward on-voltage	I _F = 40 A, T _J = 125 °C		1.4		V
		I _F = 40 A, T _J = 175 °C		1.3		
$V_{\text{GE(th)}}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 1 \text{ mA}$	5	6	7	V
I _{CES}	Collector cut-off current	$V_{GE} = 0 \text{ V}, V_{CE} = 650 \text{ V}$			25	μA
I _{GES}	Gate-emitter leakage current	V _{CE} = 0 V, V _{GE} = ±20 V			±250	nA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Cies	Input capacitance		-	5412	ı	
Coes	Output capacitance	V _{CE} = 25 V, f = 1 MHz, V _{GE} = 0 V	-	198	1	pF
Cres	Reverse transfer capacitance		-	107	1	
Qg	Total gate charge		-	210	ı	
Q _{ge}	Gate-emitter charge	Vcc = 520 V, Ic = 40 A, V _{GE} = 15 V (see Figure 29: " Gate charge test	-	39	-	nC
Q_{gc}	Gate-collector charge	circuit")	-	82	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time		-	40	-	
tr	Current rise time		-	13	-	ns
(di/dt) _{on}	Turn-on current slope	$V_{CE} = 400$ V, $I_{C} = 40$ A, $V_{GE} = 15$ V, $R_{G} = 5$ Ω (see Figure 28: " Test circuit for inductive load switching")	-	2413	-	A/µs
t _{d(off)}	Turn-off-delay time		-	142	1	20
t _f	Current fall time		-	27	-	ns

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E _{on} ⁽¹⁾	Turn-on switching energy		-	498	1	
E _{off} ⁽²⁾	Turn-off switching energy		-	363	-	μJ
E _{ts}	Total switching energy		-	861	1	
t _{d(on)}	Turn-on delay time		-	38	ı	ns
tr	Current rise time		-	14	1	115
(di/dt) _{on}	Turn-on current slope		-	2186	-	A/µs
t _{d(off)}	Turn-off-delay time	V _{CE} = 400 V, I _C = 40 A, V _{GE} = 15 V,	-	141	1	ns
t _f	Current fall time	$R_G = 5 \Omega$, $T_J = 175 ^{\circ}C$ (see Figure 28: " Test circuit for inductive load switching")	-	61	1	115
E _{on} ⁽¹⁾	Turn-on switching energy		-	1417	-	
E _{off} ⁽²⁾	Turn-off switching energy		-	764	-	μJ
Ets	Total switching energy		-	2181	-	

Notes:

Table 7: Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{rr}	Reverse recovery time		-	62	-	ns
Q _{rr}	Reverse recovery charge		-	99	-	nC
I _{rrm}	Reverse recovery current	$I_F = 40 \text{ A}, V_R = 400 \text{ V}, V_{GE} = 15 \text{ V},$ di/dt = 100 A/ μ s (see <i>Figure 28: " Test</i>	-	3.3	-	Α
dl _{rr} /dt	Peak rate of fall of reverse recovery current during t _b	circuit for inductive load switching")	-	187	-	A/µs
Err	Reverse recovery energy		-	68	-	μJ
t _{rr}	Reverse recovery time	$I_F = 40 \text{ A}, V_R = 400 \text{ V}, V_{GE} = 15 \text{ V},$ $T_J = 175 ^{\circ}\text{C}, \text{di/dt} = 100 \text{A/}\mu\text{s}$	-	310	-	ns

 $^{^{(1)}}$ Including the reverse recovery of the diode.

⁽²⁾Including the tail of the collector current.

Electrical characteristics

STGWT40H65DFB

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Q _{rr}	Reverse recovery charge	(see Figure 28: " Test circuit for inductive load switching")	-	1550	ı	nC
Irrm	Reverse recovery current		-	10	1	Α
dl _{rr} /dt	Peak rate of fall of reverse recovery current during t _b		-	70	ı	A/µs
Err	Reverse recovery energy		-	674	-	μJ

2.1 Electrical characteristics (curves)

Figure 2: Power dissipation vs. case temperature

PTOT IGBT230216EWF6GPDT
(W) VGE = 15 V, TJ ≤ 175 °C

250

150

100

50

75 100 125 150

T_c (°C)

Figure 3: Collector current vs. case temperature

I_C

IGBT230216EWF6GCCT

(A)

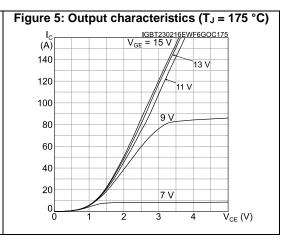
V_{GE} = 15 V, T_J ≤ 175 °C

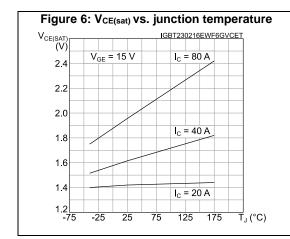
80

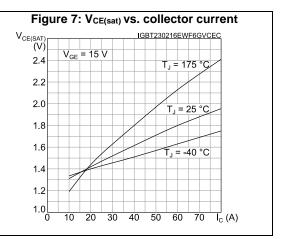
40

20

0 25 50 75 100 125 150 T_C (°C)



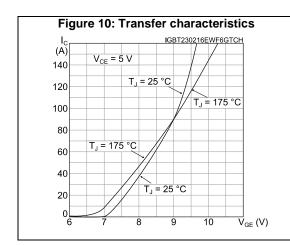


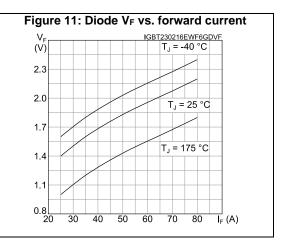


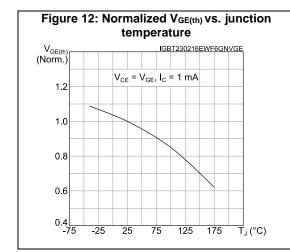
Electrical characteristics STGWT40H65DFB

Figure 8: Collector current vs. switching frequency IGBT230216EWF6GCCS I_C (A) 100 80 $T_C = 80 \, ^{\circ}C$ 60 T_C = 100 °C 40 20 Rectangular current shape (duty cycle = 0.5, V_{CC} = 400 V R_G = 5 Ω , V_{GE} = 0/15 V , T_J = 175 °C f (kHz) 10⁰ 10¹ 10^{2}

Figure 9: Forward bias safe operating area $\begin{matrix} I_C \\ (A) \end{matrix}$ $\begin{matrix} I_{C} \\ (A) \end{matrix}$ $\begin{matrix} I_{C} \\ I_{C} \\ I_{C} \end{matrix}$ $\begin{matrix} I_{C} \\ I_{C} \end{matrix}$







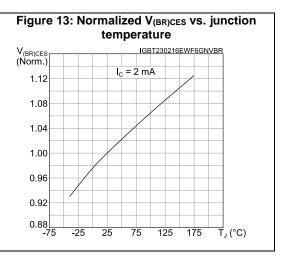


Figure 14: Capacitance variations

C
(pF)

103

102

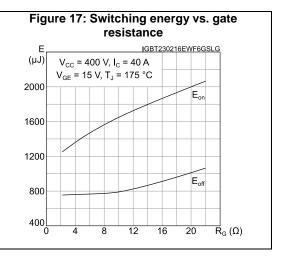
C
108

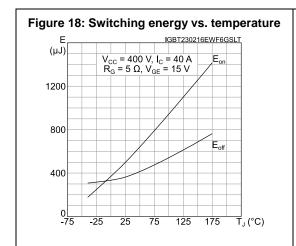
C
109

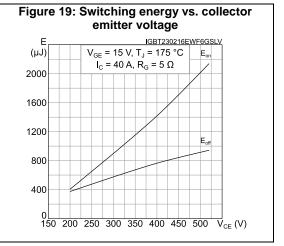
C
109

C
100

Figure 16: Switching energy vs. collector current IGBT230216EWF6GSLC (µJ) V_{GE} = 15 V, T_J = 175 °C 3000 V_{CC} = 400 V, R_G = 5 Ω 2400 E_{on} 1800 $\mathsf{E}_{\mathsf{off}}$ 1200 600 10 30 40 50 60 70







Electrical characteristics STGWT40H65DFB

Figure 20: Switching times vs. collector current $\begin{array}{c|c} & \textbf{IGBT230216EWF6GSTC} \\ \textbf{V}_{\text{CC}} = 400 \ \textbf{V}, \ \textbf{V}_{\text{GE}} = 15 \ \textbf{V} \\ \textbf{R}_{\text{G}} = 5 \ \Omega, \ \textbf{T}_{\text{J}} = 175 \ ^{\circ}\textbf{C} \end{array}$ (ns) $t_{d(off)}$ 10² $t_{d(on)}$ t, 10

20

10°L

Figure 21: Switching times vs. gate resistance IGBT230216EWF6GSTR (ns) V_{CC} = 400 V, V_{GE} = 15 V I_C = 40 A, T_J = 175 °C 10² t_f 10¹ $R_{G}(\Omega)$ 16 20

Figure 22: Reverse recovery current vs. diode current slope IGBT230216EWF6GRRC I_{rm} V_r = 400 V, I_F = 40 A 80

30 40 50 60 70 I_C (A)

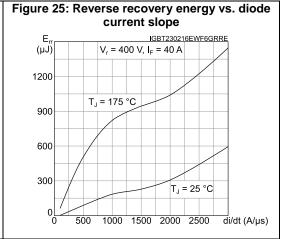
T_J = 175 °C 60 40 T_J = 25 °C 20 1500 2000 2500 di/dt (A/µs)

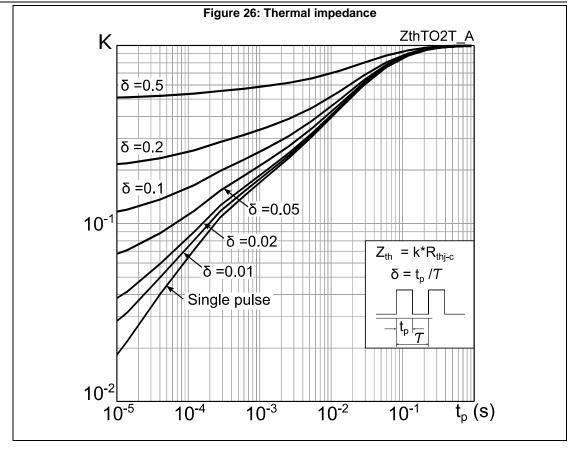
Figure 23: Reverse recovery time vs. diode current slope IGBT230216EWF6GRRT t_{rr} (ns) $V_r = 400 \text{ V}, I_F = 40 \text{ A}$ 300 250 200 150 T_J = 175 °C 100 T_J = 25 °C 50 1000 1500 2000 2500 di/dt (A/µs)

current slope IGBT230216EWF6GRRQ Q_{rr} (nC) V_r = 400 V, I_F = 40 A 4000 T_J = 175 °C 3000

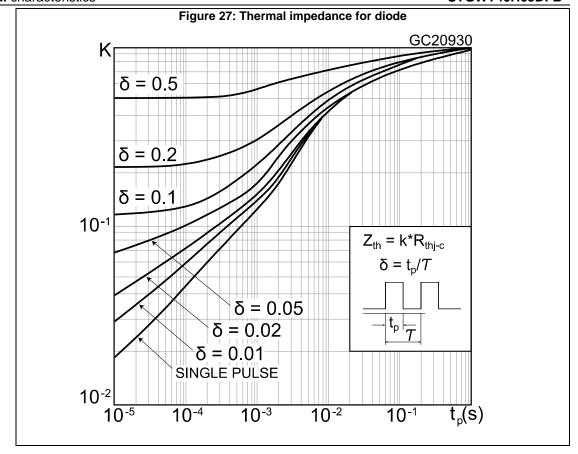
Figure 24: Reverse recovery charge vs. diode

2000 1000 T_{.1} = 25 °C 1000 1500 2000 2500 di/dt (A/µs)



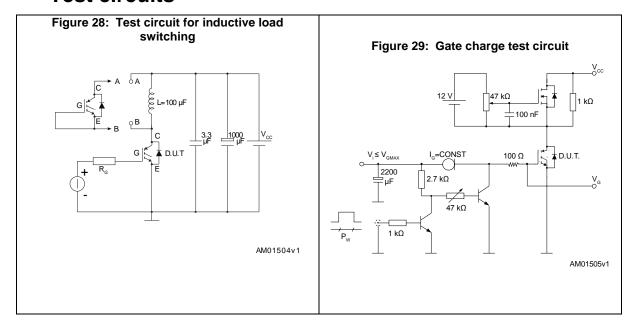


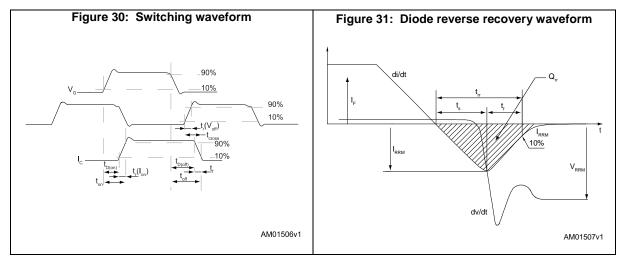
Electrical characteristics STGWT40H65DFB



STGWT40H65DFB Test circuits

3 Test circuits





Package information STGWT40H65DFB

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 TO-3P package information

Figure 32: TO-3P package outline

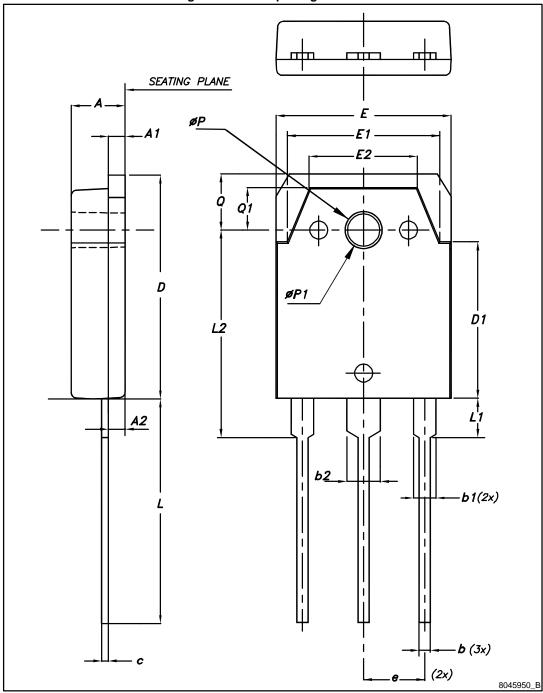


Table 8: TO-3P package mechanical data

Table 6. 10-31 package mechanical data					
Dim.		mm			
Dilli	Min.	Тур.	Max.		
А	4.60	4.80	5.00		
A1	1.45	1.50	1.65		
A2	1.20	1.40	1.60		
b	0.80	1.00	1.20		
b1	1.80	2.00	2.20		
b2	2.80	3.00	3.20		
С	0.55	0.60	0.75		
D	19.70	19.90	20.10		
D1	13.70	13.90	14.10		
Е	15.40	15.60	15.80		
E1	13.40	13.60	13.80		
E2	9.40	9.60	9.90		
е	5.15	5.45	5.75		
L	19.80	20.00	20.20		
L1	3.30	3.50	3.70		
L2	18.20	18.40	18.60		
ØP	3.30	3.40	3.50		
ØP1	3.10	3.20	3.30		
Q	4.80	5.00	5.20		
Q1	3.60	3.80	4		

STGWT40H65DFB Revision history

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
13-Jun-2016	1	Initial version. Part number previously included in datasheet DocID024363.

IMPORTANT NOTICE - PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics - All rights reserved

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

STMicroelectronics: STGWT40H65DFB